

# EH2600ETTTS-2.097152M

|  |   |   |   |
|--|---|---|---|
| <b>Lead Free</b><br><br><b>COMPLIANT</b> | <b>EU RoHS</b><br>2011/65 +<br>2015/863<br><b>COMPLIANT</b> | <b>ChinaRoHS</b><br><br><b>COMPLIANT</b> | <b>REACH</b><br><b>SVHC 163</b><br>Jun 15, 2015<br><b>COMPLIANT</b> |
|--|---|---|---|



## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 2.097152MHz  $\pm 100$ ppm -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

|  |   |
|--|---|
| <b>Nominal Frequency</b>                     | 2.097152MHz   |
| <b>Frequency Tolerance/Stability</b>         | $\pm 100$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration) |
| <b>Aging at 25°C</b>                         | $\pm 5$ ppm/year Maximum  |
| <b>Operating Temperature Range</b>           | -40°C to +85°C  |
| <b>Supply Voltage</b>                        | 3.3Vdc $\pm 10\%$   |
| <b>Input Current</b>                         | 35mA Maximum (No Load)  |
| <b>Output Voltage Logic High (Voh)</b>       | 2.7Vdc Minimum (IOH= -8mA)  |
| <b>Output Voltage Logic Low (Vol)</b>        | 0.5Vdc Maximum (IOL= +8mA)  |
| <b>Rise/Fall Time</b>                        | 6nSec Maximum (Measured at 20% to 80% of waveform)  |
| <b>Duty Cycle</b>                            | 50 $\pm 5$ (%) (Measured at 50% of waveform)  |
| <b>Load Drive Capability</b>                 | 30pF Maximum  |
| <b>Output Logic Type</b>                     | CMOS  |
| <b>Pin 1 Connection</b>                      | Tri-State (High Impedance)  |
| <b>Tri-State Input Voltage (Vih and Vil)</b> | 70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output, No Connect to enable output.   |
| <b>Absolute Clock Jitter</b>                 | $\pm 250$ pSec Maximum, $\pm 100$ pSec Typical  |
| <b>One Sigma Clock Period Jitter</b>         | $\pm 50$ pSec Maximum, $\pm 40$ pSec Typical  |
| <b>Start Up Time</b>                         | 10mSec Maximum  |
| <b>Storage Temperature Range</b>             | -55°C to +125°C   |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                                     |   |
|-------------------------------------|---|
| <b>ESD Susceptibility</b>           | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| <b>Fine Leak Test</b>               | MIL-STD-883, Method 1014, Condition A         |
| <b>Flammability</b>                 | UL94-V0                                       |
| <b>Gross Leak Test</b>              | MIL-STD-883, Method 1014, Condition C         |
| <b>Mechanical Shock</b>             | MIL-STD-883, Method 2002, Condition B         |
| <b>Moisture Resistance</b>          | MIL-STD-883, Method 1004                      |
| <b>Moisture Sensitivity</b>         | J-STD-020, MSL 1                              |
| <b>Resistance to Soldering Heat</b> | MIL-STD-202, Method 210, Condition K          |
| <b>Resistance to Solvents</b>       | MIL-STD-202, Method 215                       |
| <b>Solderability</b>                | MIL-STD-883, Method 2003                      |
| <b>Temperature Cycling</b>          | MIL-STD-883, Method 1010, Condition B         |
| <b>Vibration</b>                    | MIL-STD-883, Method 2007, Condition A         |

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION                 |
|-----|----------------------------|
| 1   | Tri-State (High Impedance) |
| 2   | Ground                     |
| 3   | Output                     |
| 4   | Supply Voltage             |

| LINE | MARKING   |
|------|---|
| 1    | ECLIPTEK  |
| 2    | 2.0971M   |
| 3    | XXXXX<br>XXXXX=Ecliptek<br>Manufacturing Identifier |

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

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## OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external  $0.1\mu\text{F}$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu\text{F}$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods



## High Temperature Infrared/Convection

|  |   |
|--|---|
| Ts MAX to TL (Ramp-up Rate)                | 3°C/Second Maximum                                |
| <b>Preheat</b>                             |   |
| - Temperature Minimum (Ts MIN)             | 150°C   |
| - Temperature Typical (Ts TYP)             | 175°C   |
| - Temperature Maximum (Ts MAX)             | 200°C   |
| - Time (ts MIN)                            | 60 - 180 Seconds                                  |
| <b>Ramp-up Rate (TL to TP)</b>             | 3°C/Second Maximum                                |
| <b>Time Maintained Above:</b>              |   |
| - Temperature (TL)                         | 217°C   |
| - Time (tL)                                | 60 - 150 Seconds                                  |
| <b>Peak Temperature (TP)</b>               | 260°C Maximum for 10 Seconds Maximum              |
| <b>Target Peak Temperature (TP Target)</b> | 250°C +0/-5°C                                     |
| <b>Time within 5°C of actual peak (tp)</b> | 20 - 40 Seconds                                   |
| <b>Ramp-down Rate</b>                      | 6°C/Second Maximum                                |
| <b>Time 25°C to Peak Temperature (t)</b>   | 8 Minutes Maximum                                 |
| <b>Moisture Sensitivity Level</b>          | Level 1   |
| <b>Additional Notes</b>                    | Temperatures shown are applied to body of device. |

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

**T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)** 5°C/Second Maximum

#### Preheat

- Temperature Minimum (T<sub>s</sub> MIN) N/A  
 - Temperature Typical (T<sub>s</sub> TYP) 150°C  
 - Temperature Maximum (T<sub>s</sub> MAX) N/A  
 - Time (t<sub>s</sub> MIN) 60 - 120 Seconds

**Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)** 5°C/Second Maximum

#### Time Maintained Above:

- Temperature (T<sub>L</sub>) 150°C  
 - Time (t<sub>L</sub>) 200 Seconds Maximum

**Peak Temperature (T<sub>P</sub>)** 240°C Maximum

**Target Peak Temperature (T<sub>P</sub> Target)** 240°C Maximum 2 Times / 230°C Maximum 1 Time

**Time within 5°C of actual peak (t<sub>p</sub>)** 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

**Ramp-down Rate** 5°C/Second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

**Additional Notes** Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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